RF COIL DESIGN FOR IMPROVED FILM UNIFORMITY OF AN ION METAL PLASMA SOURCE

ABSTRACT

[0037] The present disclosure provides a system and method for providing improved film uniformity from an ion metal plasma source. The system includes a deposition chamber and a coil. The coil is comprised of a first metal and includes opposite terminal ends disposed within the deposition chamber. At least one of the opposite terminal ends of the coil is angled less than ninety degrees.

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